

## 1000 BASE-T MODULES MODEL NO.:IH-043

### FEATURES:

- RoHS Compliant
- RoHS peak solder rating 260°C/3~5Sec
- Designed to meet IR requirement

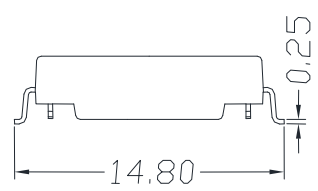
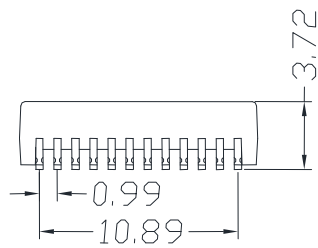
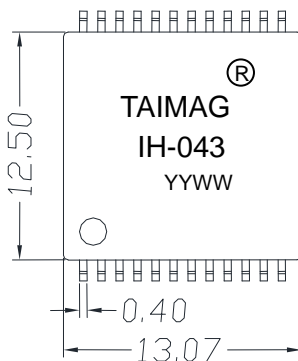
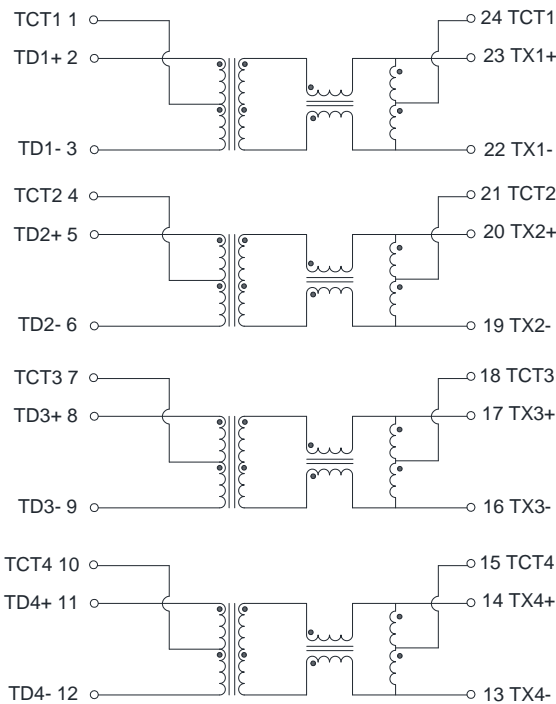
### SPECIFICATIONS: at 25°C

Operating Temperature Range: -40°C~+85°C  
 OCL:350 uH Min. @100KHz,100mV with 8mA DC Bias

Turns Ratio (TX/RX)	Insertion Loss MHz (dB MAX)	Return Loss MHz (dB Min.)					Cross talk MHz (dB Min.)			DCMR MHz (dB Min.)			Hi pot (VAC)
		1~30	40	50	60~80	100	30	60	100	30	60	100	
1CT:1CT	1~100	1~30	40	50	60~80	100	30	60	100	30	60	100	1500
1CT:1CT	-1.0	-18	-14.4	-13.1	-12	-10	-45	-40	-35	-43	-37	-33	

### SCHEMATICS:

### DIMENSION: mm ; TOLERANCE:±0.25



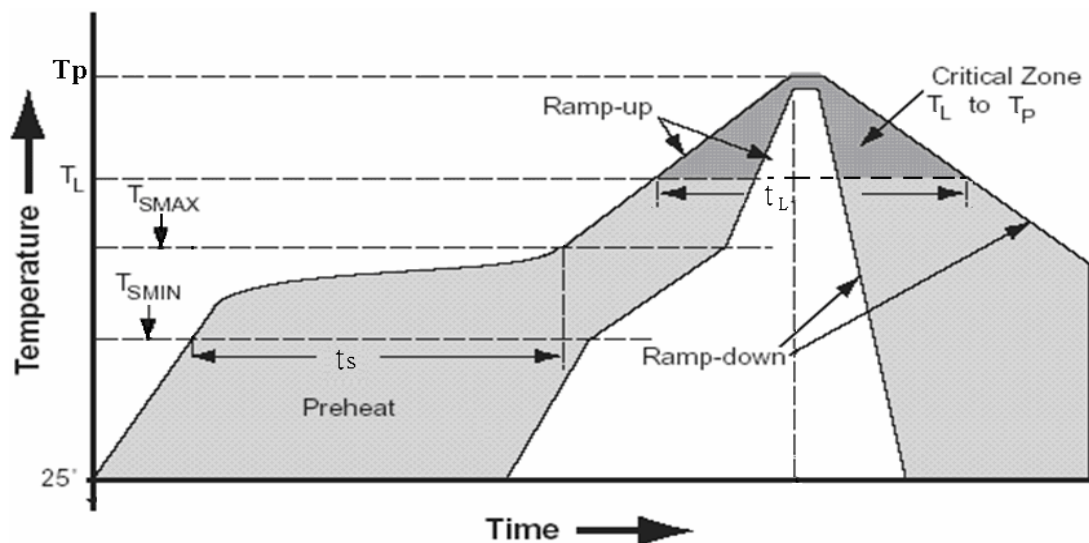
## MODEL NO.: IH-043

Solder Reflow profile for Lead-Free packages.  
Package Peak Reflow Temperatures

### Classification Reflow Profiles

Profile Feature	Lead-Free Assembly	
Average ramp-up rate( $T_L$ to $T_P$ )	3°C / Second Max.	
Preheat Temperature Min.( $T_s$ min.) Temperature Max.( $T_s$ max.) Time (min to max) ( $t_s$ )	150 °C 200 °C 60-180 sec	
$T_s$ max. to $T_L$ Ramp-up Rate	3°C / Second Max.	
Time maintained above Temperature ( $T_L$ ) Time ( $t_L$ )	200 °C 60-90 sec	
Peak Temperature ( $T_p$ ) Time within 5 °C of actual peak Temp.	260 +0 / -5 °C 3 to 5 Sec	250 +0 / -5 °C 20 to 40 Sec
Ramp-down	6°C / Second Max.	
Time 25 °C to Peak Temperature	8 minutes Max.	

### PROFILE



## MODEL NO.: IH-043

### PACKING

1. Tape & Reel : 800pcs / Reel , 4000pcs / Carton
2. Dry Pack : 1pcs  
 Product Description:(5g Silica Gel Desiccant)  
 PH: 4-8  
 Package Materials: Paper(Length 6.5±1cm , Width 5±1cm)
3. Reel Packed By Vacuum
4. Seal Per JEDEC

